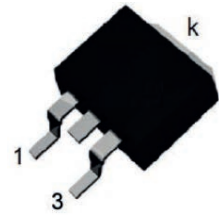


Features

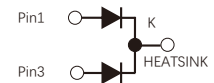
- Metal silicon junction, majority carrier conduction
- Guard ring for over-voltage protection
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High forward surge capability
- High frequency operation



TO-263 (D²PAK)

Mechanical Data

- Case: JEDEC TO-263
- Molding compound meets UL94V-0 flammability rating
- Terminals: Lead solderable per J-STD-002 and JESD22-B102
- Polarity: As marked



Schematic Diagram

Maximum Ratings (Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	60	V
Maximum Average Forward Rectified Current (see Figure.1)	Per Leg	20.0	A
	Total Device	40.0	
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method at Rated T_L)	I_{FSM}	350	A
Peak Repetitive Reverse Current per Diode at $t_p=2\mu s$ 1KHz	I_{RRM}	0.5	A
Typical Thermal Resistance ¹	$R_{\theta JC}$	0.8	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	°C

Electrical Characteristics (Per leg, $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Typ.	Max.	Unit	
Instaneous Forward Voltage ²	V_F	$I_F=20.0A$	$T_A=25^\circ C$	0.54	0.56	V
			$T_A=100^\circ C$	0.54	-	
			$T_A=125^\circ C$	0.54	-	
		$I_F=10.0A$	$T_A=25^\circ C$	0.44	-	
			$T_A=100^\circ C$	0.41	-	
			$T_A=125^\circ C$	0.40	-	
Reverse Current ³	I_R	$V_R=60V$	$T_A=25^\circ C$	100	150	μA
			$T_A=100^\circ C$	7	10	mA
			$T_A=125^\circ C$	20	50	
Typical Junction Capacitance	C_J	4V, 1MHz	1120		pF	

Notes:

1. Thermal resistance from junction to case, total device
2. Pulse test: 300 μs pulse width, 1% duty cycle
3. Pulse test: pulse width $\leq 40ms$

Ratings and Characteristics Curves

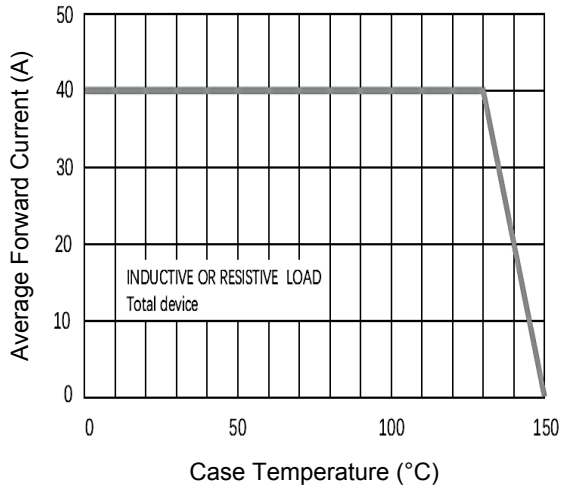


Figure 1. Forward Current Derating Curve

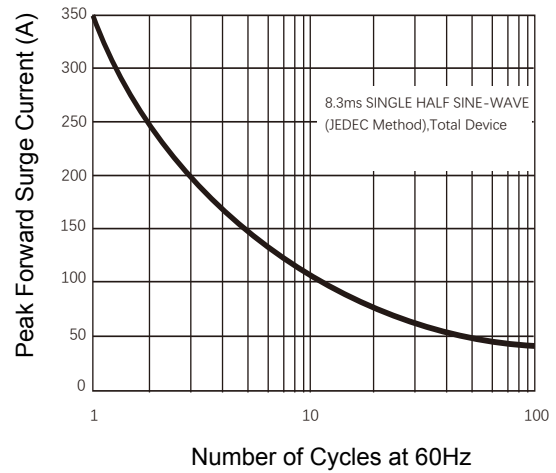


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

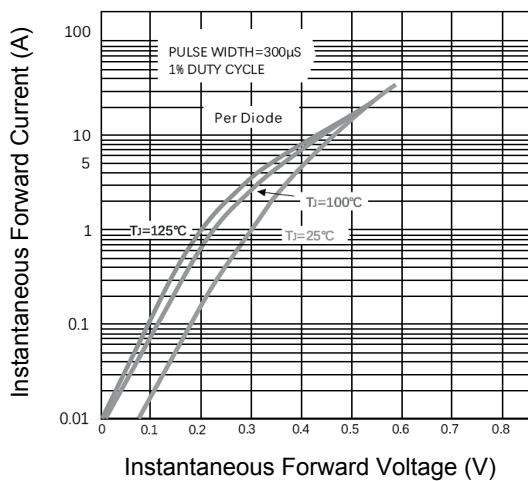


Figure 3. Typical Instantaneous Forward Characteristics

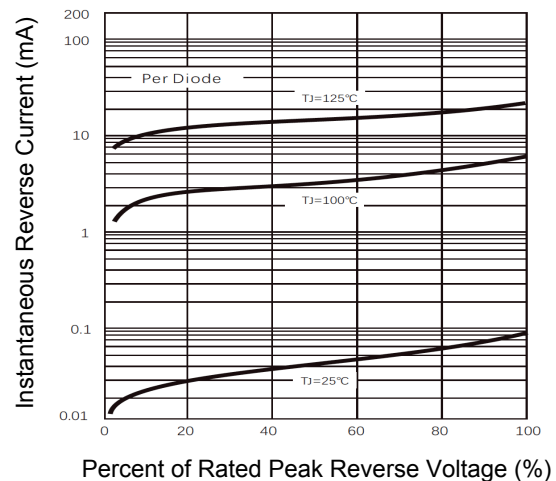


Figure 4. Typical Reverse Characteristics

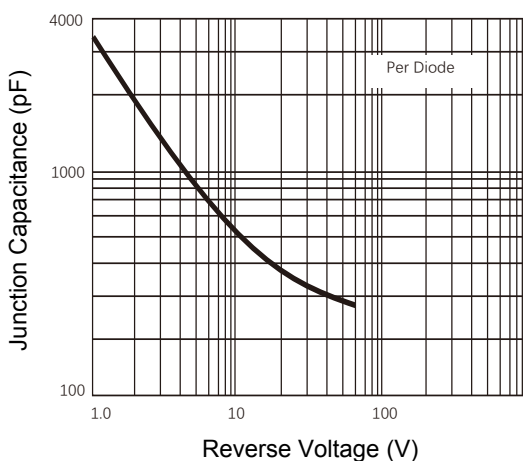
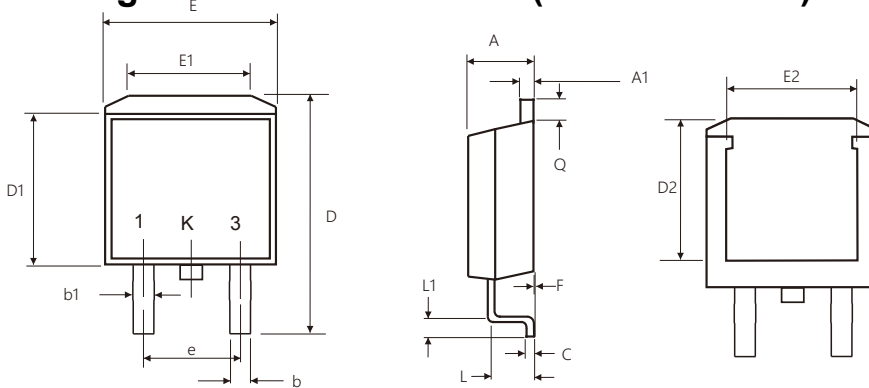


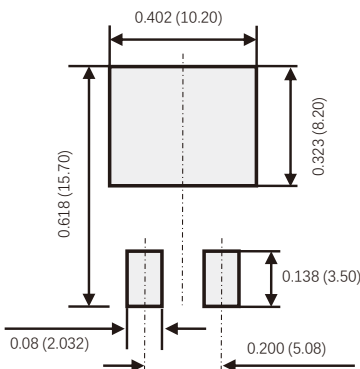
Figure 5. Typical Junction Capacitance

Package Outline Dimensions (TO-263/D²PAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.06	4.83	0.160	0.190
A1	1.14	1.40	0.045	0.055
e	4.98	5.18	0.196	0.204
b	0.69	0.94	0.027	0.037
b1	1.20	1.34	0.047	0.053
C	0.35	0.46	0.014	0.018
D	14.22	16.22	0.560	0.639
D1	8.13	9.14	0.320	0.360
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
L	2.67	3.40	0.105	0.134
L1	2.29	3.32	0.090	0.131
Q	0.92	1.68	0.036	0.066
F	0.02	0.30	0.001	0.012
D2	7.20	7.80	0.283	0.307
E2	7.60	8.20	0.299	0.323

Recommended Pad Layout



- Note:
1. Pad dimensions for reference
 2. Unit in inches (millimeters)

Order Information

Device	Package	Marking	Carrier	Quantity
GSR4060LD1	TO-263	SR4060LD1	Tape & Reel	800pcs / Reel